TEXAS INSTRUMENTS
TPS1210-Q1
JAJSOQ1 – OCTOBER 2023

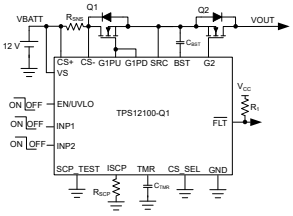
TPS1210-Q1 短絡保護および診断機能搭載、45V、車載用、低 IQ、バック・ツー・バック MOSFET スマート・ハイサイド・ドライバ

1 特長

- 車載アプリケーション向けに AEC-Q100 認定済み
  - デバイス温度グレード 1:動作時周囲温度範囲:-40℃～+125℃
- 機能安全対応
  - 機能安全システムの設計に役立つ資料を利用可能
- 3.5V～40V の入力範囲 (絶対最大定格 45V)
- 最低 -40V までの逆入力保護
- 11V チャージ・ポンプを内蔵
- 低い静止電流:35µA (動作時)
- 低シャットダウン電流 (EN/UVLO = Low):1.5µA
- 個別の制御入力 (INP1、INP2) を備えたバック・ツー・バック MOSFET 駆動用の 2 つの強力なゲート・ドライバ (2A ソース / シンク)
  - アクティブ HIGH (TPS12100-Q1) とアクティブ LOW (TPS12101-Q1) の入力を備えたバリアント
- 外付けの Rsense または可変遅延 (TMR) 付き MOSFET VDS センシングを使用する、調整可能な短絡保護 (ISCP)
- ハイサイドまたはローサイドの電流検出構成 (CS_SEL)
- 短絡フォルト時のフォルト表示 ($\overline{FLT}$)、チャージ・ポンプ低電圧、入力低電圧、および短絡コンパレータ診断 (SCP_TEST)
- 調整可能な入力低電圧誤動作防止 (UVLO)

2 アプリケーション

- 車載用 12V BMS
- DC/DC コンバータ



ハイサイド電流検出付き BMS ブレーカ

3 概要

TPS1210x-Q1 ファミリは、保護および診断機能を備えた、45V、低 IQ、スマート・ハイサイド・ドライバです。本デバイスは、動作電圧範囲が 3.5V～40V と広いため、12V のシステム設計に適しています。このデバイスは、最低 -40V の負の電源電圧に耐えられ、負荷を保護できます。

このデバイスには、個別に制御入力 (INP1、INP2) を備えた 2 つの強力な (2A) ゲート・ドライバが搭載されており、共通ソース構成でバック・ツー・バック MOSFET を駆動できます。TPS12100-Q1 はアクティブ HIGH の制御入力を、TPS12101-Q1 はアクティブ LOW の制御入力をそれぞれ備えています。

このデバイスは、調整可能な短絡保護機能を備えています。自動リトライおよびラッチオフ・フォルト動作は設定可能です。電流検出は、外付けの検出抵抗、または MOSFET VDS センシングのいずれかを使用して実行できます。CS_SEL ピン入力を使用して、ハイサイドまたはローサイドの電流検出抵抗構成が可能です。このデバイスは、SCP_TEST 入力の外部制御を使用した、内蔵の短絡コンパレータを診断する機能も備えています。

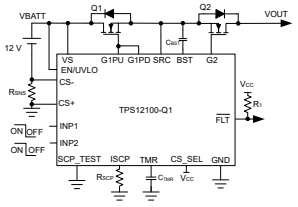
動作時の静止電流が 35µA (代表値) と低いため、常時オンのシステム設計が可能です。EN/UVLO が LOW で、静止電流が 1.5µA (代表値) まで低減します。

TPS1210x-Q1 は、19 ピンの VSSOP パッケージで供給されます。

製品情報

部品番号	パッケージ(1)	パッケージ・サイズ (2)
TPS12100-Q1、TPS12101-Q1	DGX (VSSOP、19)	5.1mm × 3.0mm

(1) 利用可能なすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。
(2) パッケージ・サイズ (長さ×幅) は公称値であり、該当する場合はピンも含まれます。



ローサイド電流検出付き BMS ブレーカ

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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

DATE	REVISION	NOTES
October 2023	*	Initial Release

5 Device Comparison

	TPS12100-Q1	TPS12101-Q1
Input controls (INP1, INP2)	Active High logic	Active Low logic

6 Pin Configuration and Functions

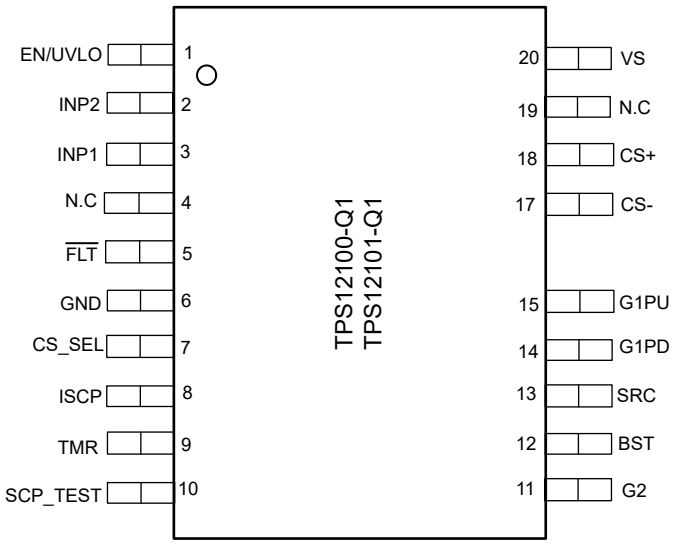

図 6-1. VSSOP 19-Pin DGX Top View

表 6-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	TPS1210x-Q1 DGX-19 (VSSOP)		
EN/UVLO	1	I	EN/UVLO Input. A voltage on this pin above 1.21 V enables normal operation. Forcing this pin below 0.3 V shuts down the device reducing quiescent current to approximately 1.6 µA (typical). Optionally connect to the input supply through a resistive divider to set the undervoltage lockout. When EN/UVLO is left floating an internal pull down of 100 nA pulls EN/UVLO low and keeps the device in shutdown state.
INP2	2	I	Input Signal for external charge FET control. In TPS12100-Q1 drive INP2 high to drive G2 high. Drive INP2 low to pull G2 low. INP2 has an internal weak 100-nA pulldown to GND to keep G2 pulled low to SRC when INP2 is left floating. In TPS12101-Q1 drive INP2 low to drive G2 high. Drive INP2 high to pull G2 low. INP2 has an internal weak pulldown of 100 nA to GND to keep G2 high when INP2 is left floating.
INP1	3	I	Input Signal for external charge FET control. In TPS12100-Q1 drive INP1 high to drive G1PU high. Drive INP1 low to pull G1PD low. INP1 has an internal weak pulldown of 100 nA to GND to keep G1PD pulled to SRC when INP1 is left floating. In TPS12101-Q1, drive INP1 low to drive G1PU high. Drive INP1 high to pull G1PD low. INP1 has an internal weak pull down of 100 nA to GND to keep G1PU high when INP1 is left floating.
N.C	4	—	No connect

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表 6-1. Pin Functions (続き)

PIN		TYPE[1]	DESCRIPTION
NAME	TPS1210x-Q1 DGX-19 (VSSOP)		
$\overline{FLT}$	5	O	Open Drain Fault Output. This pin asserts low during short-circuit fault, charge pump UVLO, input UVLO and during SCP comparator diagnosis. If $\overline{FLT}$ feature is not desired then connect it to GND.
GND	6	G	Connect GND to system ground
CS_SEL	7	I	Current sense select input. Connect this pin to ground to activate high side current sense. Drive this pin to > 2 V to activate low side current sensing. CS_SEL has an internal weak pull down of 100 nA to GND.
ISCP	8	I	Short-circuit detection setting. A resistor across ISCP to GND sets the short circuit current comparator threshold. If short-circuit protection feature is not desired then connect CS+, CS– , VS pins together and connect ISCP, TMR pins to GND.
TMR	9	I	Fault Timer Input. A capacitor across TMR pin to GND sets the delay time for short-circuit fault turn-off . Leave this pin open for fastest response setting. If short-circuit protection feature is not desired then connect CS+, CS–, VS pins together and connect ISCP, TMR pins to GND.
SCP_TEST	10	I	Internal short-circuit comparator (SCP) diagnosis input. When SCP_TEST is driven low to high with INP1 pulled high, the internal SCP comparator operation is checked. $\overline{FLT}$ goes low and G1PD gets pulled to SRC if SCP comparator is functional. Connect SCP_TEST pin to GND if this feature is not desired. SCP_TEST has an internal weak pulldown of 100 nA to GND.
G2	11	O	Charging FET gate drive output. This pin has 1.69-A peak source and 2-A sink capacity. Leave the G2 pin floating if the G2 drive functionality is unused.
BST	12	O	High Side Bootstrapped Supply. An external capacitor with a minimum value of > $Q_{g(tot)}$ of the external FET must be connected between this pin and SRC.
SRC	13	O	Source connection of the external FET
G1PD	14	O	High Current Gate Driver Pull-Down. This pin pulls down to SRC. For the fastest turn-off, tie this pin directly to the gate of the external high side MOSFET.
G1PU	15	O	High Current Gate Driver Pull-Up. This pin pulls up to BST. Connect this pin to G1PD for maximum gate drive transition speed. A resistor can be connected between this pin and the gate of the external MOSFET to control the in-rush current during turn-on.
CS-	17	I	Current sense negative input
CS+	18	I	Current sense positive input
N.C	19	—	No connect
VS	20	Power	Supply pin of the controller

(1) I = input, O = output, I/O = input and output, P = power, G = Ground

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7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Input pins	VS, CS+, CS– to GND	–40	45	V
	SRC to GND	–40	45	
	G1PU, G1PD, G2, BST to SRC	–0.3	19	
	ISCP, TMR, SCP_TEST to GND	–0.3	5.5	
	EN/UVLO, INP1, INP2, CS_SEL to GND, $V_{(VS)}$ > 0 V	–1	45	
	EN/UVLO, INP1, INP2, CS_SEL to GND, $V_{(VS)}$ ≤ 0 V	$V_{(VS)}$	(40 + $V_{(VS)}$)	
	CS+ to CS–	–1	45	
	$\overline{FLT}$ to GND	–1	20	
Sink current	$I_{(\overline{FLT})}$		10	mA
	$I_{(CS+)}$ to $I_{(CS–)}$, 1 ms	–100	100	mA
Output pins	G1PU, G1PD, G2, BST to GND	–40	60	V
Operating junction temperature, T_j (2)		–40	150	°C
Storage temperature, T_{stg}		–40	150	

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.

7.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002(1)		±2000	V
		Charged device model (CDM), per AEC Q100-011	Corner pins (EN/UVLO, VS, SCP_TEST, G2)	±750	
			Other pins	±500	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	NOM	MAX	UNIT
Input pins	VS to GND	3.5		40	V
	EN/UVLO, INP1, INP2, CS_SEL to GND	0		40	
Output pins	$\overline{FLT}$ to GND	0		15	
External capacitor	VS, SRC to GND	22			nF
	BST to SRC	0.1			µF
Tj	Operating Junction temperature(2)	–40		150	°C

(1) Recommended Operating Conditions are conditions under which the device is intended to be functional. For specifications and test conditions, see Electrical Characteristics.
(2) High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.

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7.4 Thermal Information

THERMAL METRIC(1)		TPS1210-Q1 DGX 19 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	92.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	28.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	47.5	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	47.2	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

7.5 Electrical Characteristics

T_J = –40 °C to +125°C. $V_{(VS)}$ = 12 V, $V_{(BST-SRC)}$ = 11 V, $V_{(SRC)}$ = 0 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY VOLTAGE						
VS	Operating input voltage		3.5		40	V
$I_{(Q)}$	Total system quiescent current, $I_{(GND)}$	$V_{(EN/UVLO)}$ = 2 V		35		µA
$I_{(SHDN)}$	SHDN current, $I_{(GND)}$	$V_{(EN/UVLO)}$ = 0 V, $V_{(SRC)}$ = 0 V		1.5		µA
ENABLE, UNDERVOLTAGE LOCKOUT (EN/UVLO), SHORT CIRCUIT COMPARATOR TEST (SCP_TEST) INPUT						
$V_{(UVLOR)}$	UVLO threshold voltage, rising			1.24		V
$V_{(UVLOF)}$	UVLO threshold voltage, falling			1.14		V
$V_{(ENR)}$	Enable threshold voltage for low Iq shutdown, rising				1.02	V
$V_{(ENF)}$	Enable threshold voltage for low Iq shutdown, falling		0.3			V
$V_{(SCP\_TEST)}$	SCP test mode rising threshold				1.02	V
$V_{(SCP\_TEST)}$	SCP test mode rising threshold		0.3			V
$I_{(EN/UVLO)}$	Enable input leakage current	$V_{(EN/UVLO)}$ = 12 V		180		nA
CHARGE PUMP (BST–SRC)						
$V_{(BST-SRC\_ON)}$	Charge Pump turn on voltage	$V_{(EN/UVLO)}$ = 2 V	10			V
$V_{(BST-SRC\_OFF)}$	Charge Pump turn off voltage	$V_{(EN/UVLO)}$ = 2 V			11.8	V
$V_{(BST\_UVLOR)}$	$V_{(BST-SRC)}$ UVLO voltage threshold, rising	$V_{(EN/UVLO)}$ = 2 V			9.5	V
$V_{(BST\_UVLOF)}$	$V_{(BST-SRC)}$ UVLO voltage threshold, falling	$V_{(EN/UVLO)}$ = 2 V	7.2			V
$I_{(SRC)}$	SRC pin leakage current	$V_{(EN/UVLO)}$ = 2 V, $V_{(INP1)}$ = $V_{(INP2)}$ = 0 V		1		µA
GATE DRIVER OUTPUTS (G1PU, G1PD, G2)						
$I_{(G1PU)}$, $I_{(G2\_src)}$	Peak Source Current			1.69		A
$I_{(G1PD)}$, $I_{(G2\_snk)}$	Peak Sink Current			2		A
$V_{(G1\_GOOD)}$	VGS Good Threshold for G1 Gate Drive			7.5		V
SHORT CIRCUIT PROTECTION (ISCP)						
$V_{(SCP)}$	SCP threshold	$R_{(ISCP)}$ = 145 kΩ	240	300	360	mV
		$R_{(ISCP)}$ = 32.5 kΩ		75		mV
		$R_{(ISCP)}$ = 15 kΩ		40		mV
DELAY TIMER (TMR)						
$I_{(TMR\_SRC\_CB)}$	TMR source current			80		µA

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7.5 Electrical Characteristics (続き)

T_J = –40 ℃ to +125℃. $V_{(VS)}$ = 12 V, $V_{(BST-SRC)}$ = 11 V, $V_{(SRC)}$ = 0 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(TMR\_SRC\_FLT)}$	TMR source current			2.2		µA
$I_{(TMR\_SNK)}$	TMR sink current			2.5		µA
$V_{(TMR\_SC)}$				1.1		V
$V_{(TMR\_LOW)}$				0.2		V
$N_{(A-R\ Count)}$				32		
INPUT CONTROLS (INP1, INP2), CURRENT SENSE SELECT (CS_SEL) AND FAULT FLAG ($\overline{FLT}$)						
$R_{(\overline{FLT})}$	$\overline{FLT}$ Pull-down resistance			70		Ω
$V_{(INP1\_H)}$, $V_{(INP2\_H)}$		TPS12100-Q1 Only			2	V
$V_{(INP1\_L)}$, $V_{(INP2\_L)}$		TPS12100-Q1 Only	0.8			V
$V_{(CS\_SEL\_H)}$	CS_SEL threshold for low side sensing				2	V
$V_{(CS\_SEL\_L)}$	CS_SEL threshold for high side sensing		0.8			V

7.6 Switching Characteristics

T_J = –40 ℃ to +125℃. $V_{(VS)}$ = 12 V, $V_{(BST-SRC)}$ = 11 V, $V_{(SRC)}$ = 0 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{G1PU(INP1\_H)}$	INP1 turn on propogation Delay	INP1 ↑ to G1PU ↑, C_L = 47 nF		1		µs
$t_{G2(INP2\_H)}$	INP2 turn on propogation Delay	INP2 ↑ to G2 ↑, C_L = 47 nF		5		µs
$t_{G1PD(INP1\_L)}$	INP1 turn off propogation Delay	INP1 ↓ to G1PD ↓, C_L = 47 nF		1		µs
$t_{G2(INP2\_L)}$	INP2 Turn off propogation Delay	INP2 ↓ to G2 ↓, C_L = 47 nF		5		µs
$t_{G1PD(UVLO\_OFF)}$	UVLO turn off Propogation Delay	UVLO ↓ to G1PD ↓, C_L = 47 nF		7.5		µs
t_{SC}	Hard short-circuit Protection propogation Delay	$V_{(CS+-CS-)}$ ↑ $V_{(SCP)}$ to G1PD ↓, C_L = 47 nF, $C_{(TMR)}$ = Open		4		µs
t_{SC_PUS}	Short circuit protection propogation delay during power up with output short circuit	$C_{(TMR)}$ = Open			10	µs

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8 Parameter Measurement Information

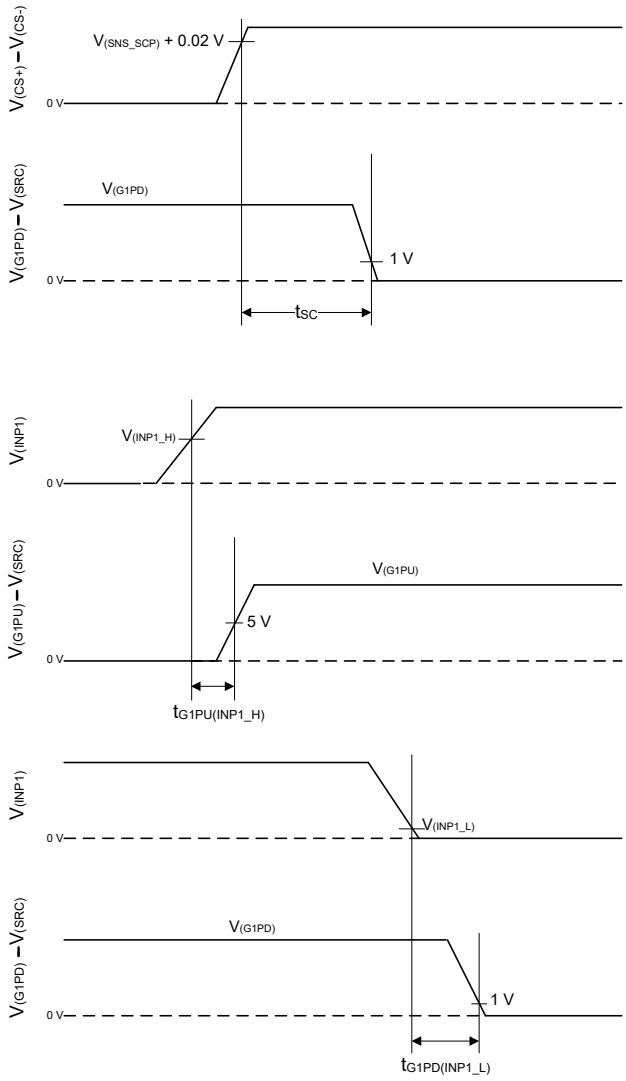


図 8-1. Timing Waveforms

9 Detailed Description

9.1 Overview

The TPS1210x-Q1 family is a 45-V, low IQ, smart high side driver with protection and diagnostics. With wide operating voltage range of 3.5 V – 40 V, the device is designed for 12-V, system designs. The device can withstand and protect the loads from negative supply voltages down to –40 V.

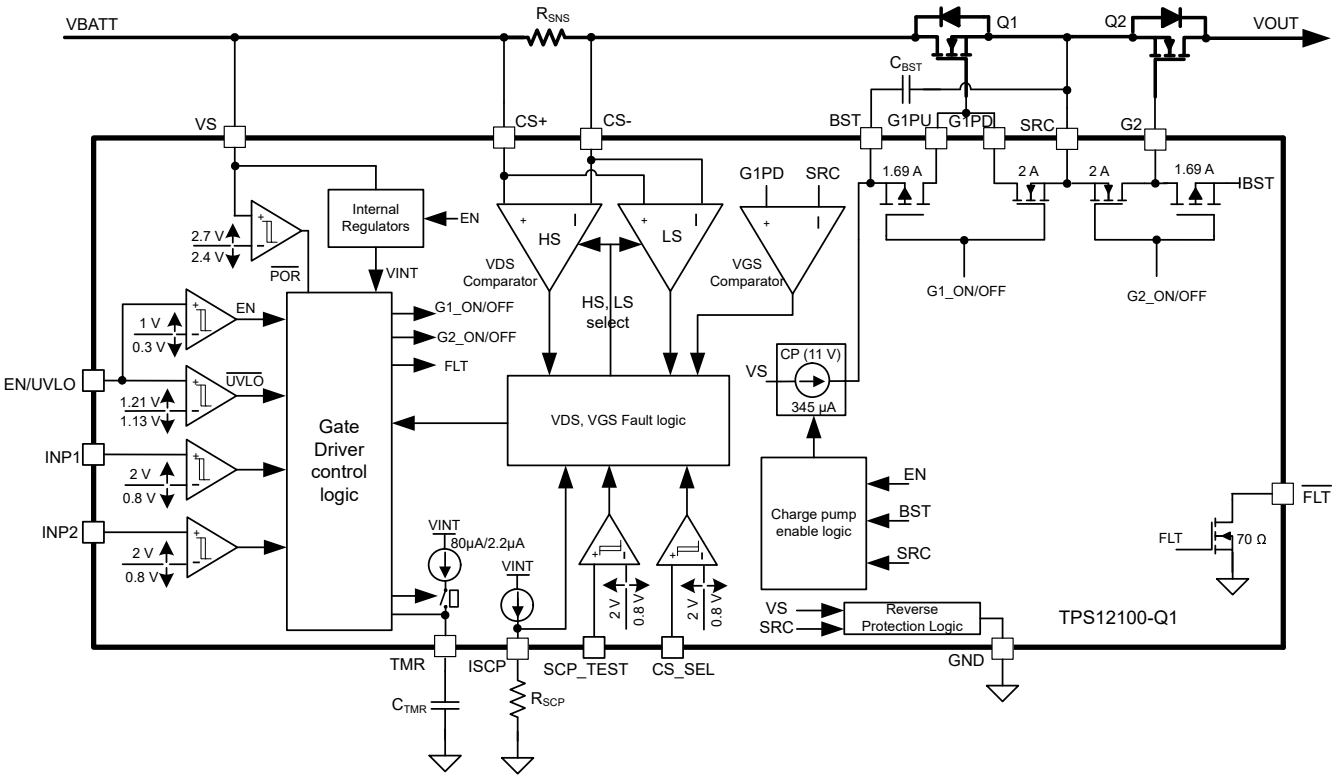
The device has two strong (2-A) GATE drivers with separate control inputs (INP1, INP2) to drive back-to-back MOSFETs in common source configuration. Strong GATE driving enables power switching using parallel FETs in high current system designs. TPS12100-Q1 has active high control inputs and TPS12101-Q1 has active low control inputs.

The device provides configurable short-circuit protection using ISCP and TMR pins for adjusting the threshold and response time respectively. Auto-retry and latch-off fault behavior can be configured. With TPS1210x-Q1, current sensing an be done either by an external sense resistor or by MOSFET VDS sensing. High side or low side current sense resistor configuration is possible by using CS_SEL pin input. Diagnosis of the integrated short circuit comparator is possible using external control on SCP_TEST input.

The device indicates fault ($\overline{FLT}$) on open drain output during short circuit, charge pump undervoltage, and input undervoltage conditions.

Low Quiescent Current of 35 µA in operation enables always ON system designs. Quiescent current reduces to 1.5 µA (typical) with EN/UVLO low.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Charge Pump and Gate Driver Output (VS, G1PU, G1PD, G2, BST, SRC)

図 9-1 shows a simplified diagram of the charge pump and gate driver circuit implementation. The device houses two strong 1.69-A/2-A peak source/sink gate drivers enabling paralleling of FETs in high power system designs ensuring minimum transition time in saturation region. A 11-V, 345-µA charge pump is derived from VS terminal and charges the external boot-strap capacitor, C_{BST} that is placed across the gate driver (BST and SRC).

VS is the supply pin to the controller. With VS applied and EN/UVLO pulled high, the charge pump turns ON and charges the C_{BST} capacitor. After the voltage across C_{BST} crosses $V_{(BST\_UVLOR)}$, the GATE driver section is activated. The device has a 1-V (typical) UVLO hysteresis to ensure chattering less performance during initial GATE turn ON. Choose C_{BST} based on the external FET Q_G and allowed dip during FET turn-ON. The charge pump remains enabled until the BST to SRC voltage reaches 11.8 V, typically, at which point the charge pump is disabled decreasing the current draw on the VS pin. The charge pump remains disabled until the BST to SRC voltage discharges to 10 V typically at which point the charge pump is enabled. The voltage between BST and SRC continue to charge and discharge between 11.8 V and 10 V as shown in the 図 9-2.

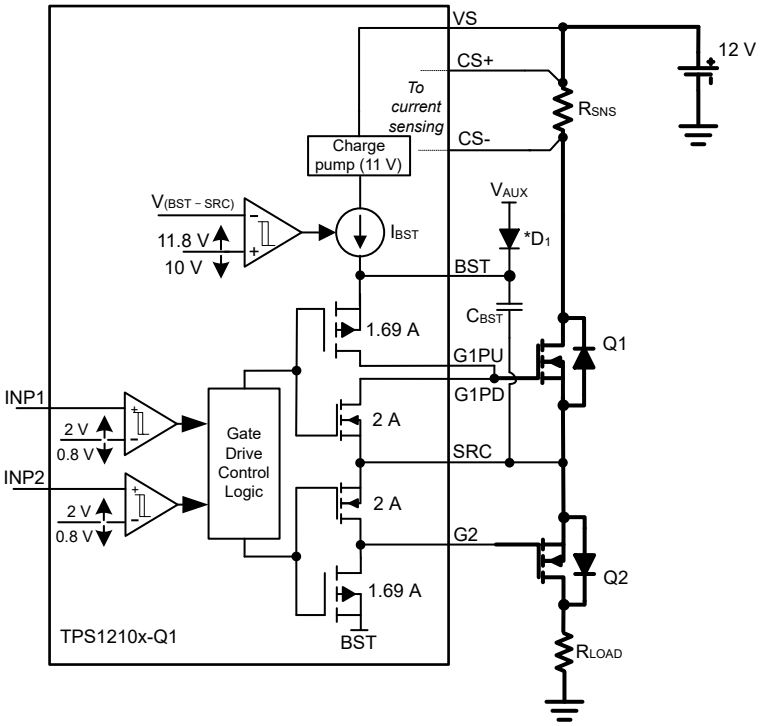


図 9-1. Gate Drivers

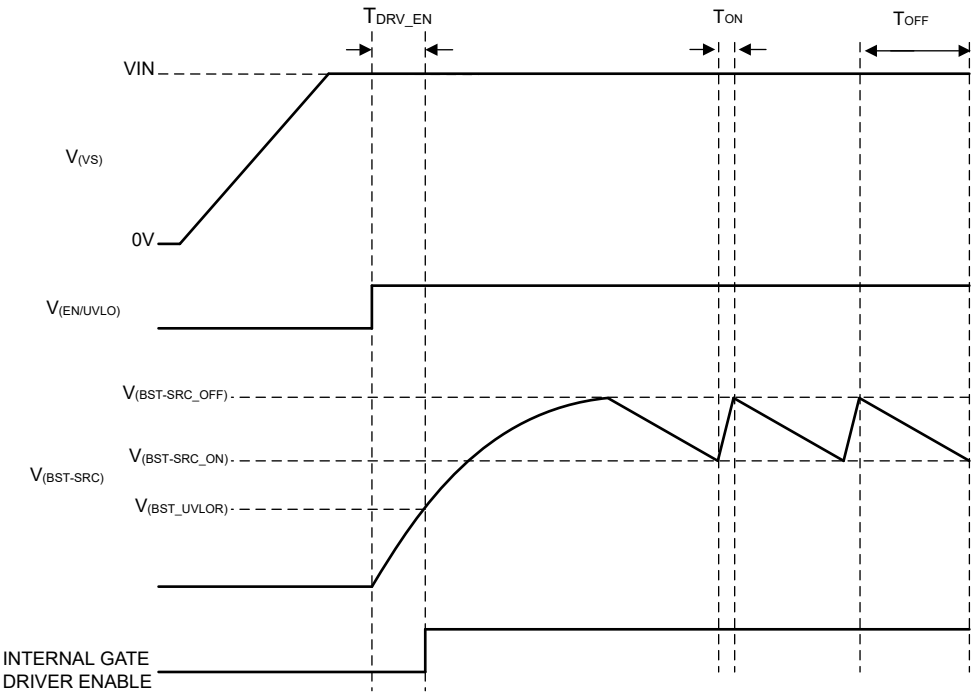


図 9-2. Charge Pump Operation

Use the following equation to calculate the initial gate driver enable delay:

$$T_{DRV\_EN} = \frac{C_{BST} \times V_{(BST\_UVLOR)}}{345\ \mu A} \quad (1)$$

Where,

C_{BST} is the charge pump capacitance connected across BST and SRC pins.

$V_{(BST\_UVLOR)}$ = 9.5 V (maximum).

If T_{DRV_EN} must be reduced then pre-bias BST terminal externally using an external V_{AUX} supply through a low leakage diode D_1 as shown in . With this connection, T_{DRV_EN} reduces to 400 µs. TPS12100-Q1 application circuit with external supply to BST is shown in 図 9-3.

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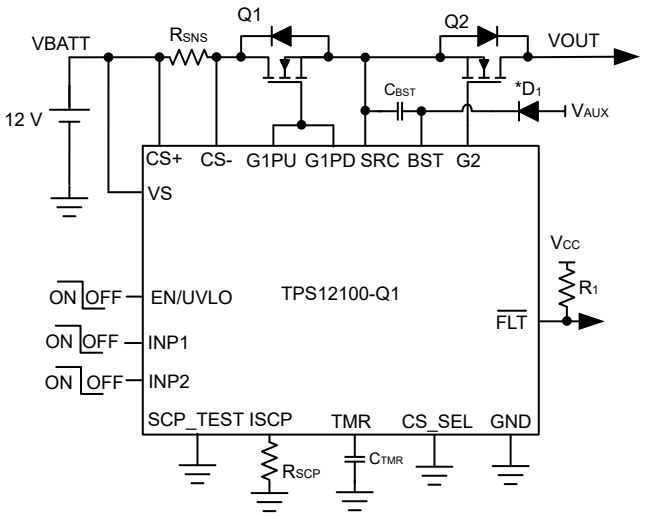

図 9-3. TPS12100-Q1 Application Circuit With External Supply to BST

注

V_{AUX} can be supplied by external regulated supply ranging between 8 V and 18 V.

9.3.2 Capacitive Load Driving Using FET Gate (G1PU, G1PD) Slew Rate Control

For limiting inrush current during turn-ON of the external FET (Q1) with capacitive loads, use R_1, R_2, C_1 as shown in 図 9-4. The R_1 and C_1 components slow down the voltage ramp rate at the gate of Q1 FET. The FET source follows the gate voltage resulting in a controlled voltage ramp across the output capacitors.

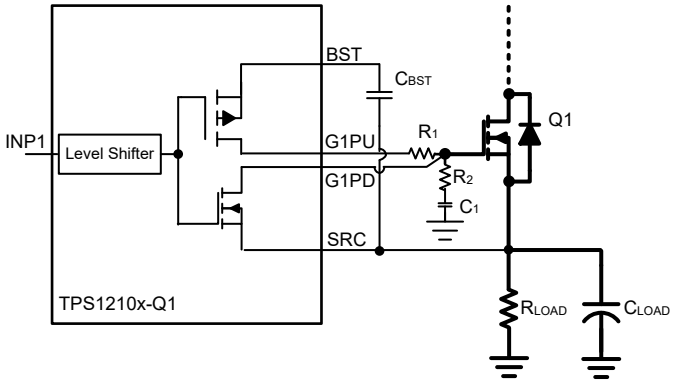

図 9-4. Inrush Current Limiting Using G1 Gate Drive

Use the 式 2 to calculate the inrush current during turn-ON of the FET.

$$I_{INRUSH} = C_{LOAD} \times \frac{V_{BATT}}{T_{charge}} \quad (2)$$

$$C_1 = \frac{0.63 \times V_{(BST\ -\ SRC)} \times C_{LOAD}}{R_1 \times I_{INRUSH}} \quad (3)$$

Where,

C_{LOAD} is the load capacitance.

VBATT is the input voltage and T_{charge} is the charge time.

$V_{(BST-SRC)}$ is the charge pump voltage (11 V),

Use a damping resistor R_2 (approximately 10 Ω) in series with C_1. 式 3 can be used to compute required C_1 value for a target inrush current. A 100-kΩ resistor for R_1 can be a good starting point for calculations.

Connecting G1PD pin of TPS1210x-Q1 directly to the gate of the Q1 FET ensures fast turn-OFF without any impact of R_1 and C_1 components.

C_1 results in an additional loading on C_{BST} to charge during turn-ON. Use below equation to calculate the required C_{BST} value:

$$C_{BST} = \frac{Q_{g(total)}}{\Delta V_{BST}} + 10 \times C_1 \quad (4)$$

Where,

$Q_{g(total)}$ is the total gate charge of the FET,

ΔV_{BST} (1 V typical) is the ripple voltage across BST to SRC pins.

9.3.3 Short-Circuit Protection

The TPS1210x-Q1 feature adjustable short-circuit protection. The threshold and response time can be adjusted using R_{SCP} resistor and C_{TMR} capacitor respectively. The device senses the voltage across CS+ and CS– pins.

These pins can be connected across an external high and low side current sense resistor (R_{SNS}) or across the FET drain and source terminals for FET RDSON sensing as shown in 図 9-5, 図 9-6 and 図 9-7 respectively.

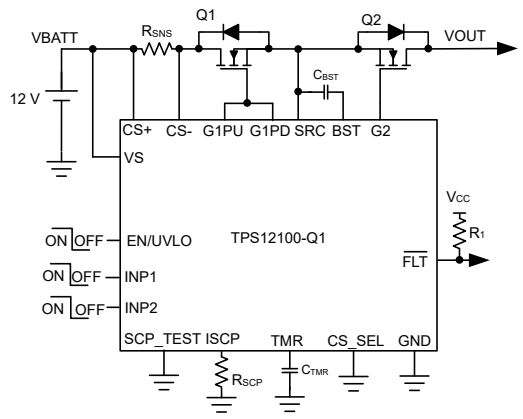

図 9-5. TPS12100-Q1 Application Circuit With External Sense Resistor RSNS based High Side Current Sensing

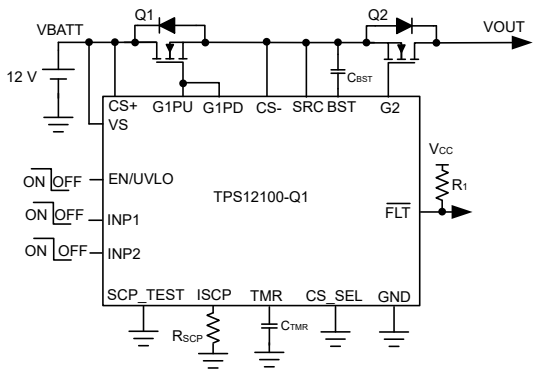

図 9-6. TPS12100-Q1 Application Circuit With MOSFET RDSON based Current Sensing

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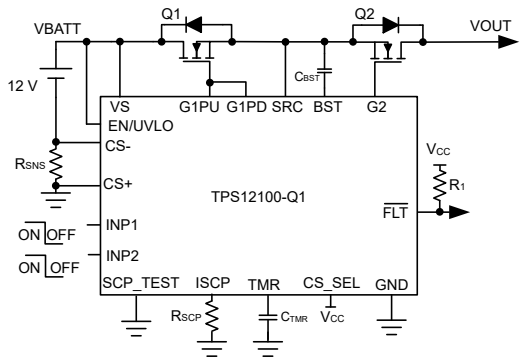

図 9-7. TPS12100-Q1 Application Circuit with External Sense Resistor RSNS based Low Side Current Sensing

Set the short-circuit detection threshold using an external R_{SCP} resistor across ISCP and GND pins. Use 式 5 to calculate the required R_{SCP} value:

$$R_{SCP}\left(\Omega\right) = \frac{\left(I_{SC} \times R_{SNS} - 10\ mV\right)}{2\ \mu A} \quad (5)$$

Refer to 式 9 in *Application Limitations* section for update in equation in final revision of IC.

Where,

R_{SNS} is the current sense resistor value or the FET R_{DSON} value.

I_{SC} is the desired short-circuit current level.

The short-circuit protection response is fastest with no C_{TMR} cap connected across TMR and GND pins.

With the device powered ON and EN/UVLO, INP1 pulled high, During Q1 turn-ON, first VGS of external FET Q1 (G1 gate drive) is sensed by monitoring the voltage across G1PD to SRC. Once G1PD to SRC voltage raises above $V_{(G1\_GOOD)}$ threshold which ensures that the external FET is enhanced, then the SCP comparator output is monitored. If the sensed voltage across CS+ and CS– exceeds the short-circuit set point ($V_{(SCP)}$), G1PD pulls low to SRC and $\overline{FLT}$ asserts low. Subsequent events can be set either to be auto-retry or latch off as described in following sections.

9.3.3.1 Short-Circuit Protection With Auto-Retry

The C_{TMR} programs the short-circuit protection delay (t_{SC}) and auto-retry time (t_{RETRY}). After the voltage across CS+ and CS– exceeds the set point, the C_{TMR} starts charging with 80-µA pullup current.

After C_{TMR} charges to $V_{(TMR\_SC)}$, G1PD pulls low to SRC and $\overline{FLT}$ asserts low providing warning on impending FET turn-OFF. Post this event, the auto-retry behavior starts. The C_{TMR} capacitor starts discharging with 2.5-uA pulldown current. After the voltage reaches $V_{(TMR\_LOW)}$ level, the capacitor starts charging with 2.2-uA pullup. After 32 charging-discharging cycles of C_{TMR} the FET turns ON back and $\overline{FLT}$ de-asserts.

The device retry time (t_{RETRY}) is based on C_{TMR} for the first time as per 式 7.

Use 式 6 to calculate the C_{TMR} capacitor to be connected across TMR and GND.

$$C_{TMR} = \frac{I_{TMR} \times t_{SC}}{1.1} \quad (6)$$

Where,

I_{TMR} is internal pullup current of 80 µA.

t_{SC} is the desired short-circuit response time.

Leave TMR floating for fastest short-circuit response time.

$$t_{RETRY} = 22.7 \times 10^6 \times C_{TMR} \quad (7)$$

If the short-circuit pulse duration is below t_{SC} then the FET remains ON and C_{TMR} gets discharged using internal pulldown switch.

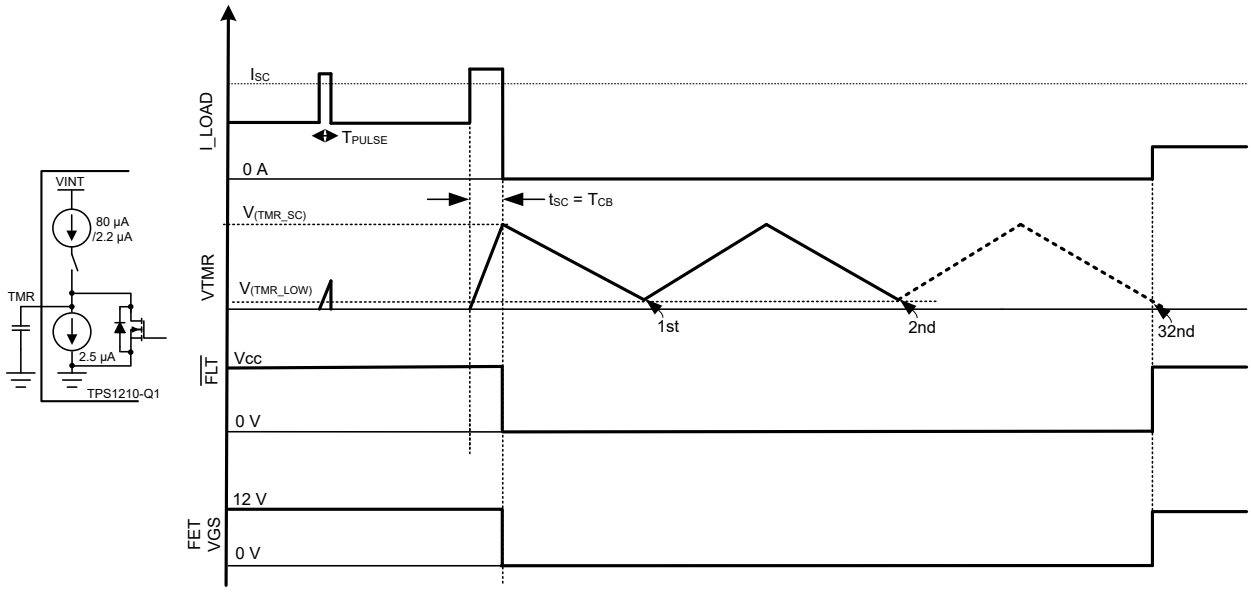

図 9-8. Short-Circuit Protection With Auto-Retry

9.3.3.2 Short-Circuit Protection With Latch-Off

Connect an approximately 100-kΩ resistor across C_{TMR} as shown in 図 9-9. With this resistor, during the charging cycle, the voltage across C_{TMR} gets clamped to a level below $V_{(TMR\_SC)}$ resulting in a latch-off behavior and $\overline{FLT}$ asserts low at same time.

Use 式 8 to calculate C_{TMR} capacitor to be connected between TMR and GND for R_{TMR} = 100 kΩ.

$$C_{TMR} = \frac{t_{SC}}{R_{TMR} \times \ln\left(\frac{1}{1 - \frac{1}{1.1}}{R_{TMR} \times 80\ \mu A}\right)} \quad (8)$$

Where,

I_{TMR} is internal pullup current of 80 µA.

t_{SC} is the desired short-circuit response time.

Toggle INP or EN/UVLO (below $V_{(ENF)}$) or power cycle VS below $V_{(VS\_PORF)}$ to reset the latch. At low edge, the timer counter is reset and C_{TMR} is discharged. G1PU pulls up to BST when INP is pulled high.

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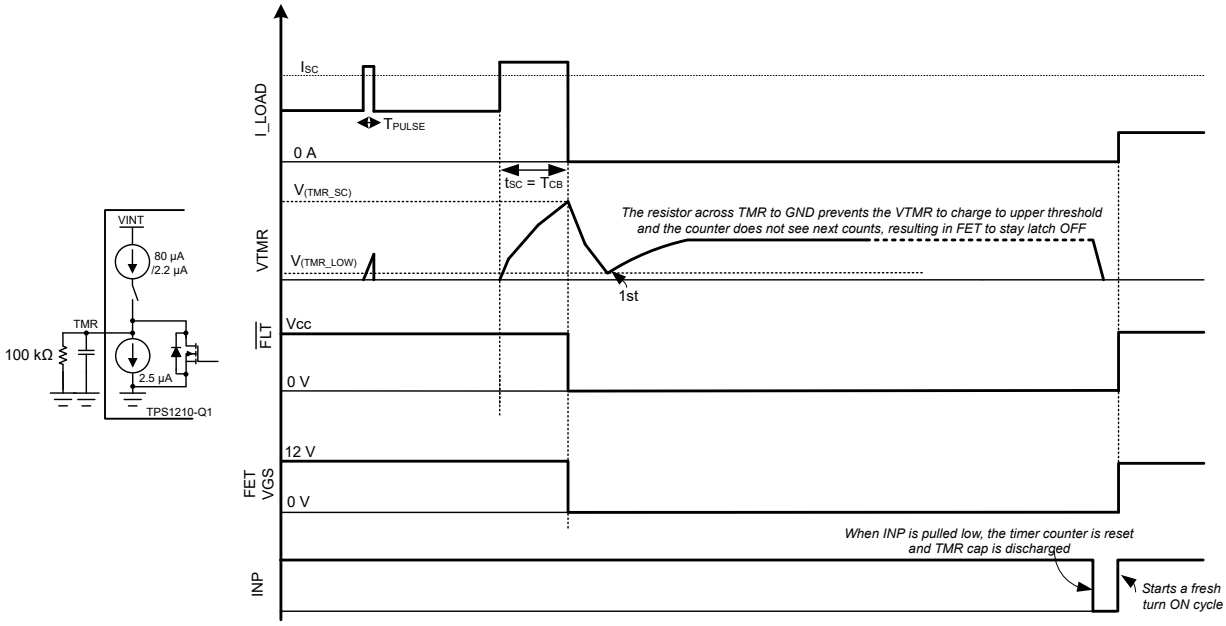

図 9-9. Short-Circuit Protection With Latch-Off

9.3.4 Undervoltage Protection (UVLO)

TPS1210x-Q1 has an accurate undervoltage protection (< ±2%) using EN/UVLO pin providing robust protection. Connect a resistor ladder as shown in 図 9-10 for undervoltage protection threshold programming.

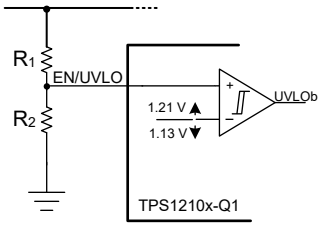

図 9-10. Programming Undervoltage Protection

9.3.5 Reverse Polarity Protection

The TPS1210x-Q1 devices features integrated reverse polarity protection to protect the device from failing during input and output reverse polarity faults. Reverse polarity faults occur during installation and maintenance of the end equipments. The device is tolerant to reverse polarity voltages down to –45 V both on input and on the output.

On the output side, the device can see transient negative voltages during regular operation due to output cable harness inductance kickbacks when the switches are turned OFF. In such systems the output negative voltage level is limited by the output side TVS or a diode.

9.3.6 Short-Circuit Protection Diagnosis (SCP_TEST)

In the safety critical designs, the short-circuit protection (SCP) feature and the diagnosis are important.

The TPS1210x-Q1 features the diagnosis of the internal short-circuit protection. When SCP_TEST is driven low to high, then a voltage is applied internally across the SCP comparator inputs to simulate a short-circuit event.

The comparator output controls the gate drive (G1PU/G1PD) and also the $\overline{FLT}$. If the gate drive goes low (with initially being high) and $\overline{FLT}$ also goes low, then this action indicates that the SCP is good otherwise is to be treated as the SCP feature is not functional.

If the SCP_TEST feature is not used, then connect SCP_TEST pin to GND.

9.3.7 TPS1210x-Q1 as a Simple Gate Driver

図 9-11 shows application schematics of TPS1210x-Q1 as a simple gate driver in load connect-disconnect switch driving back-to-back FETs topology. The short-ciruit protection feature is disabled.

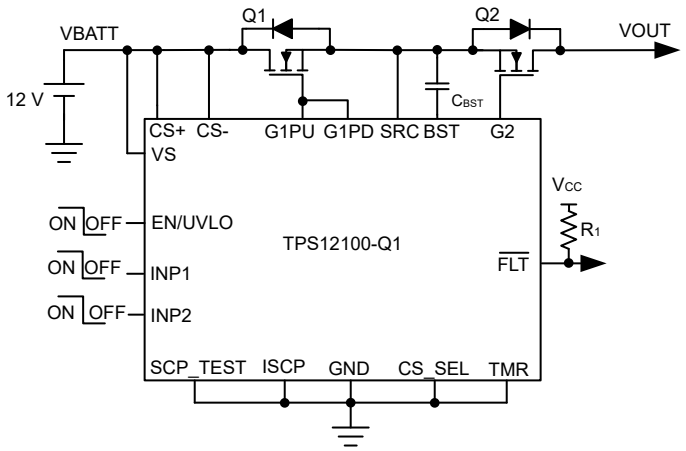

図 9-11. TPS12100-Q1 Application Circuit for Simple Gate Driver

9.4 Device Functional Modes

The TPS1210x-Q1 has two modes of operation. Active mode and low IQ shutdown mode.

If the EN/UVLO pin voltage is greater than $V_{(ENR)}$ rising threshold, then the device is in active mode. In active state the internal charge pump is enabled, gate drivers, all the protection and diagnostic features are enabled.

If the EN/UVLO voltage is pulled below $V_{(ENF)}$ falling threshold, the device enters into low IQ shutdown mode. In this mode, the charge pump, gate drivers and all the protection features are disabled. The gate drive and external FETs turn OFF. The TPS1210x-Q1 consumes low IQ of 1.5 µA (typical) in this mode.

ADVANCE INFORMATION

10 Application and Implementation

注

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10.1 Application Information

The TPS1210x-Q1 family is a 45-V, low IQ, smart high side driver with protection and diagnostics. The TPS1210x-Q1 device architecture is design to drive and control back-to-back N-Channel MOSFETs independently in common source configuration with separate control inputs (INP1, INP2), which makes TPS1210x-Q1 an excellent choice to realize circuit breaker in battery management system (BMS). The strong (2-A) GATE drivers enable switching parallel MOSFETs in high current applications such as circuit breaker in powertrain (DC/DC converter), driving loads in power distribution unit, circuit breaker in 12-V BMS, and so forth.

The TPS1210x-Q1 device provides configurable short-circuit protection using ISCP and TMR pins for adjusting the threshold and response time respectively. Auto-retry and latch-off fault behavior can be configured. By using CS+ and CS– pins, current sensing can be done either by an external sense resistor or by MOSFET VDS sensing. High side or low side current sense resistor configuration is possible by using CS_SEL pin input. The device also features diagnosis of the internal short circuit comparator using external control on SCP_TEST input.

The following design procedure can be used to select the supporting component values based on the application requirement.

10.1.1 Application Limitations

This section highlights some limitations in the application which were identified during bench evaluation of the existing TPS1210-Q1 silicon on the evaluation module (EVM).

10.1.1.1 Short-Circuit Protection Delay

In application designs with high side current sense configurations as shown in 図 9-5 and 図 9-6 with C_{TMR} = Open, the short-circuit protection delay during power up with output short circuited does not match the specified maximum value of 10 µs.

Testing has shown that the actual short-circuit protection delay during power up by EN/UVLO signal is approximately 70 µs. This increase in protection delay still allows for the TPS1210-Q1 to operate as designed, but results in larger power dissipation in the external MOSFET during output short-circuit scenario.

A design fix must be included in the final version of the IC.

10.1.1.2 Short-Circuit Protection Threshold

The minimum short-circuit protection threshold is limited to 30 mV.

A design update is planned in the final revision of the IC to extend the minimum threshold down to 20 mV. Due to the design update there will be a change of R_{SCP} resistor formula and the revised formula will be as per the 式 9:

$$R_{SCP}\left(\Omega\right) = \frac{\left(I_{SC} \times R_{SNS} - 19\ mV\right)}{2\ \mu A} \tag{9}$$

Lowest SCP threshold setting will be limited to 20 mV.

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10.2 Typical Application: Circuit Breaker in Battery Management System (BMS) using Low Side Current Sense

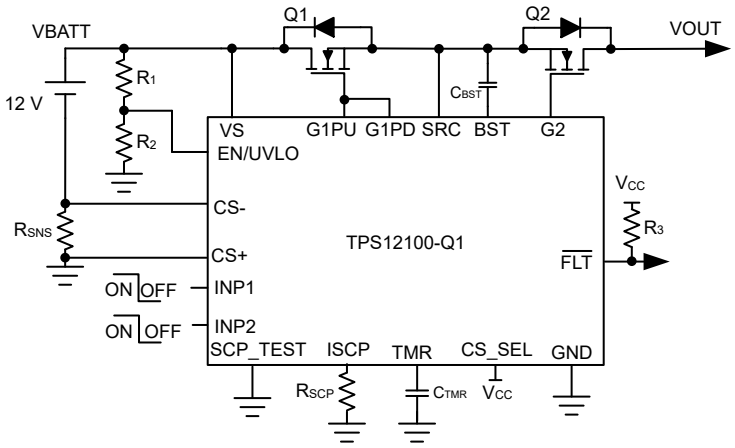

図 10-1. Typical Application Schematic: BMS Circuit Breaker With Low Side Current Sense

ADVANCE INFORMATION

10.2.1 Design Requirements

The following table shows the design parameters for this application example.

表 10-1. Design Parameters

PARAMETER	VALUE
Typical input voltage, V_{IN}	12 V
Undervoltage lockout set point, VIN_{UVLO}	6.5 V
Maximum load current, I_{OUT}	25 A
Short-circuit protection threshold, I_{SC}	40 A
Short-circuit protection delay (t_{SC})	1 ms
Fault response	Auto-retry
Current sensing	Low-side

10.2.2 Detailed Design Procedure

Selection of Current Sense Resistor, R_{SNS}

The recommended range of the overcurrent protection threshold voltage, $V_{(SCP)}$, extends from 30 mV to 300 mV. Values near the low threshold of 30 mV can be affected by the system noise. Values near the upper threshold of 300 mV can cause high power dissipation in the current sense resistor. To minimize both the concerns, 40 mV is selected as the short-circuit protection threshold voltage. Use the following equation to calculate the current sense resistor, R_{SNS}.

$$R_{SNS} = \frac{V_{(SCP)}}{I_{SC}} \tag{10}$$

The next smaller available sense resistor 1 mΩ, 1% is chosen.

To improve signal to noise ratio or for better short-circuit protection accuracy, higher short-circuit protection threshold voltage, $V_{(SCP)}$ can be selected.

Programming the Short-Circuit Protection Threshold – R_{SCP} Selection

The R_{SCP} sets the short-circuit protection threshold. Use the following equation to calculate the value.

$$R_{SCP}\left(\Omega\right) = \frac{\left(I_{SC} \times R_{SNS} - 10\ \text{mV}\right)}{2\ \mu\text{A}} \tag{11}$$

To set 30-A as short-circuit protection threshold, R_{SCP} value is calculated to be 15 kΩ.

Choose the closest available standard value: 15 kΩ, 1%.

Refer to 式 9 in *Application Limitations* section for update in equation in final revision of IC.

In case where large di/dt is involved, the system and layout parasitic inductances can generate large differential signal voltages between CS+ and CS- pins. This action can trigger false short-circuit protection and nuisance trips in the system. To overcome such scenario, TI suggests to add placeholder for RC filter components across sense resistor (R_{SNS}) and tweak the values during test in the real system. The RC filter components should not be used in current sense designs by MOSFET VDS sensing to avoid impact on the short-circuit protection response.

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Programming the Short-Circuit Protection Delay – C_{TMR} Selection

For the design example under discussion, overcurrent transients are allowed for 1-ms duration. This short-circuit protection delay, t_{SC} can be set by selecting appropriate capacitor C_{TMR} from TMR pin to ground. Use the following equation to calculate the value of C_{TMR} to set 1 ms for t_{SC}.

$$C_{TMR} = \frac{80\,\mu \times t_{SC}}{1.1} = 72.72\ \text{nF} \quad (12)$$

Choose closest available standard value: 82 nF, 10%.

Selection of MOSFETs, Q_1 and Q_2

For selecting the MOSFET Q_1 and Q_2 important electrical parameters are the maximum continuous drain current I_D, the maximum drain-to-source voltage $V_{DS(MAX)}$, the maximum drain-to-source voltage $V_{GS(MAX)}$, and the drain-to-source ON-resistance R_{DSON}.

The maximum continuous drain current, I_D, rating must exceed the maximum continuous load current.

The maximum drain-to-source voltage, $V_{DS(MAX)}$, must be high enough to withstand the highest voltage seen in the application. Considering 35 V as the maximum application voltage, MOSFETs with V_{DS} voltage rating of 40 V is designed for this application.

The maximum V_{GS} TPS1210-Q1 can drive is 13 V, so a MOSFET with 15-V minimum V_{GS} rating must be selected.

To reduce the MOSFET conduction losses, lowest possible $R_{DS(ON)}$ is preferred.

Based on the design requirements, BUK7S1R0-40H is selected and the ratings are:

- 40-V $V_{DS(MAX)}$ and 20-V $V_{GS(MAX)}$
- $R_{DS(ON)}$ is 0.88-mΩ typical at 10-V V_{GS}
- Maximum MOSFET $Q_{g(total)}$ is 137 nC

Selection of Bootstrap Capacitor, C_{BST}

The internal charge pump charges the external bootstrap capacitor (connected between BST and SRC pins) with approximately 345 µA. Use the following equation to calculate the minimum required value of the bootstrap capacitor for driving two BUK7S1R0-40H MOSFETs.

$$C_{BST} = \frac{Q_{g(total)}}{1\,\text{V}} = 274\ \text{nF} \quad (13)$$

Choose closest available standard value: 330 nF, 10 %.

Setting the Undervoltage Lockout

The undervoltage lockout (UVLO) can be adjusted using an external voltage divider network of R_1 and R_2 connected between VS, EN/UVLO and GND pins of the device. The values required for setting the undervoltage and overvoltage are calculated by solving 式 14.

$$V_{(UVLOR)} = \frac{R_2}{(R_1 + R_2)} \times VIN_{UVLO} \quad (14)$$

For minimizing the input current drawn from the power supply, TI recommends to use higher values of resistance for R_1 and R_2. However, leakage currents due to external active components connected to the resistor string can add error to these calculations. So, the resistor string current, $I(R_{12})$ must be chosen to be 20 times greater than the leakage current of UVLO pin.

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From the device electrical specifications, $V_{(UVLOR)}$ = 1.21 V. From the design requirements, VIN_{UVLO} is 6.5 V. To solve the equation, first choose the value of R_1 = 470 kΩ and use 式 14 to solve for R_2 = 107.5 kΩ. Choose the closest standard 1% resistor values: R_1 = 470 kΩ, and R_2 = 105 kΩ.

10.2.3 Application Curves

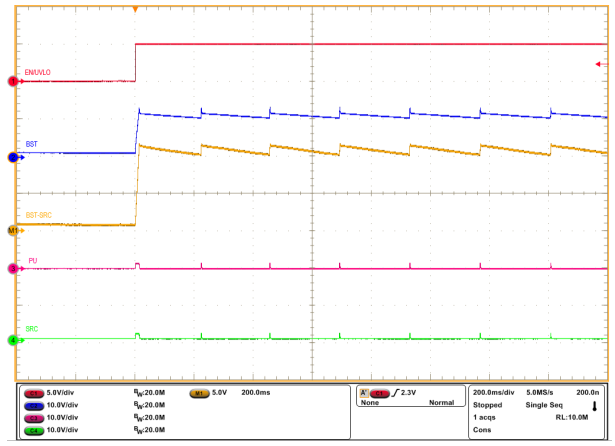

図 10-2. Start-Up Profile of Bootstrap Voltage with INP1=INP2 = GND and C_{BST} = 470 nF

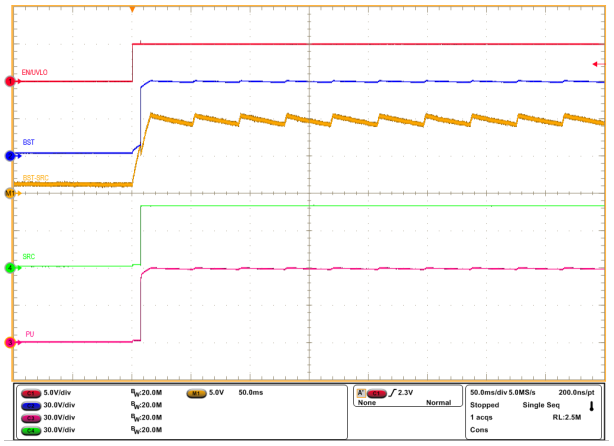

図 10-3. Start-Up Profile of Bootstrap Voltage with INP1=INP2 = HIGH and C_{BST} = 470 nF

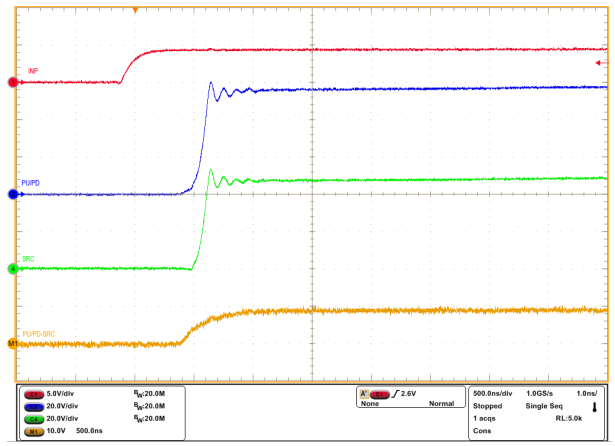

図 10-4. Turn-ON Response of TPS12100-Q1 for INP1 -> LOW to HIGH and C_{BST} = 470 nF

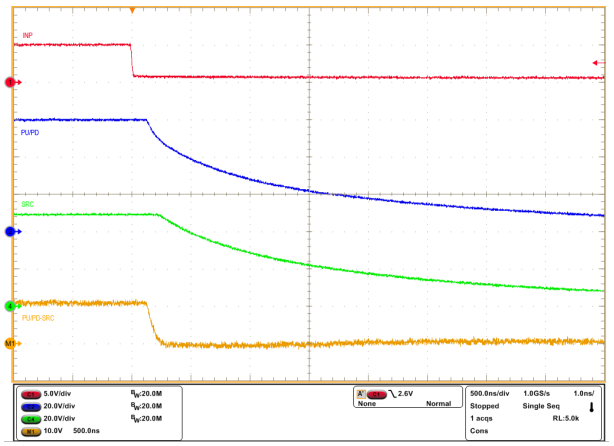

図 10-5. Turn-OFF Response of TPS12100-Q1 for INP1 -> HIGH to LOW and C_{BST} = 470 nF

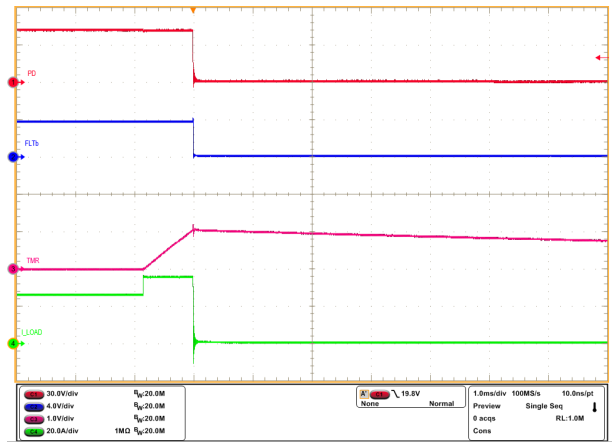

図 10-6. Overcurrent Response of TPS12100-Q1 for a Load Step from 25 A to 35 A with 30-A Overcurrent Protection Setting

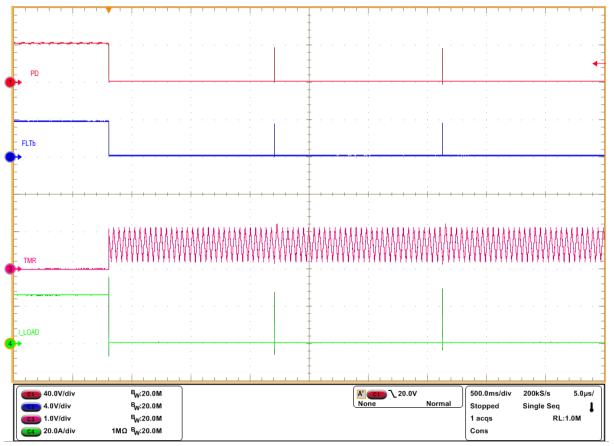

図 10-7. Auto-Retry Response of TPS12100-Q1 for an Overcurrent Fault

ADVANCE INFORMATION

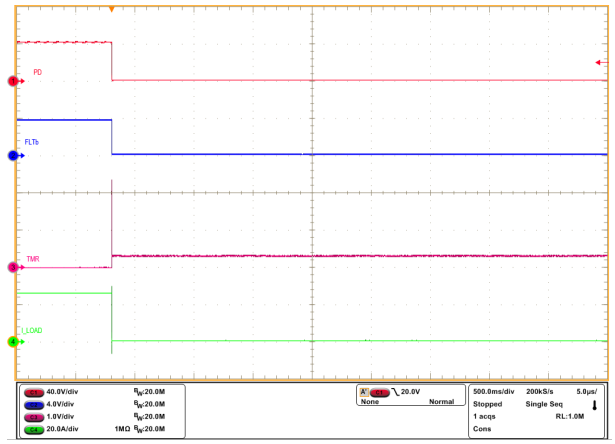

図 10-8. Latch-Off Response of TPS12100-Q1 for an Overcurrent Fault

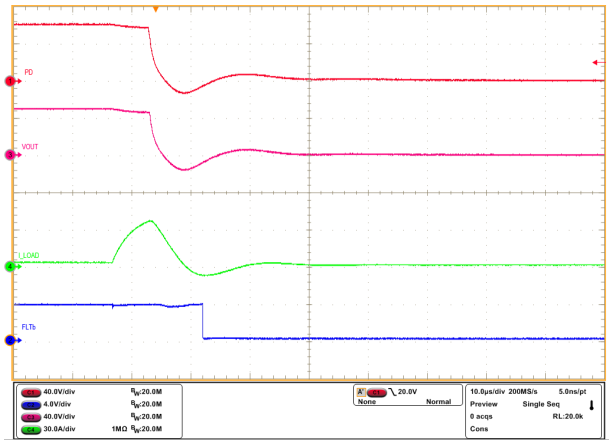

図 10-9. Output Short-Circuit Response of TPS12100-Q1 Device

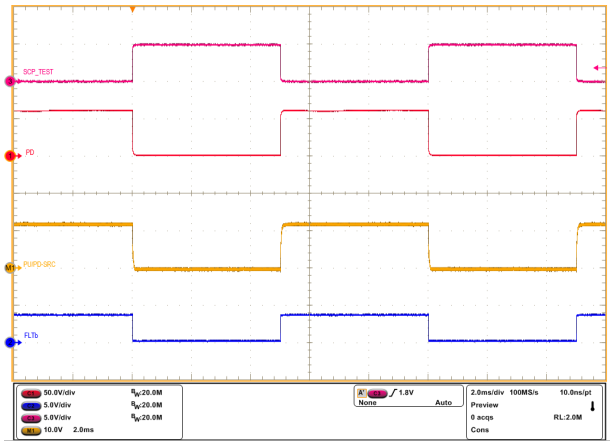

図 10-10. Short-Circuit Protection Diagnosis Test Response of TPS12100-Q1

10.3 Power Supply Recommendations

When the external MOSFETs turn-OFF during the conditions such as INP1 control, overcurrent protection causing an interruption of the current flow, the input parasitic line inductance generates a positive voltage spike on the input and output parasitic inductance generates a negative voltage spike on the output. The peak amplitude of voltage spikes (transients) depends on the value of inductance in series to the input or output of the device. These transients can exceed the *Absolute Maximum Ratings* of the device if steps are not taken to address the issue. Typical methods for addressing transients include:

- Use of a TVS diode and input capacitor filter combination across input to and GND to absorb the energy and dampen the positive transients.
- Use of a diode or a TVS diode across the output and GND to absorb negative spikes.

The TPS1210-Q1 gets powered from the VS pin. Voltage at this pin must be maintained above $V_{(VS\_PORR)}$ level to ensure proper operation. If the input power supply source is noisy with transients, then TI recommends to place a R_{VS} - C_{VS} filter between the input supply line and VS pin to filter out the supply noise. TI recommends R_{VS} value around 100 Ω.

In case where large di/dt is involved, the system and layout parasitic inductances can generate large differential signal voltages between CS+ and CS- pins. This action can trigger false short-circuit protection and nuisance trips in the system. To overcome such scenario, TI suggests to add placeholder for RC filter components across sense resistor (R_{SNS}) and tweak the values during test in the real system. The RC filter components must not be used in current sense designs by MOSFET VDS sensing to avoid impact on the short-circuit protection response.

The following figure shows the circuit implementation with optional protection components.

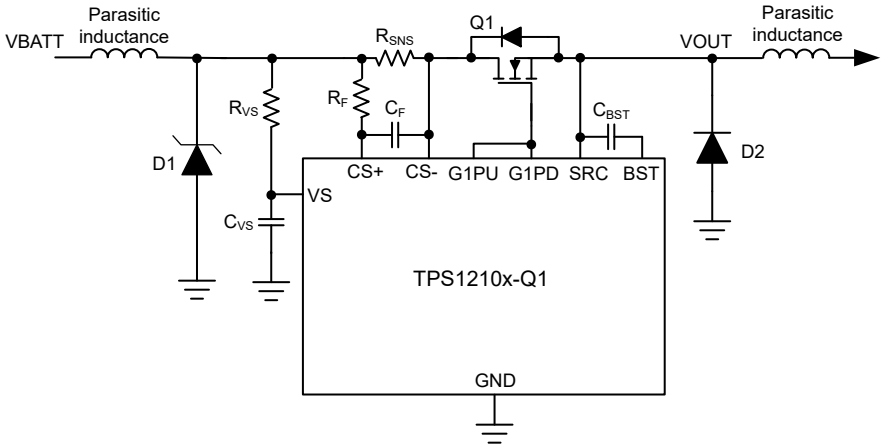

図 10-11. Circuit Implementation With Optional Protection Components For TPS1210-Q1

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10.4 Layout

10.4.1 Layout Guidelines

- Place the sense resistor (R_{SNS}) close to the TPS1210x-Q1 and then connect R_{SNS} using the Kelvin techniques. Refer to *Choosing the Right Sense Resistor Layout* for more information on the Kelvin techniques.
- Choose a 0.1 µF or higher value ceramic decoupling capacitor between VS terminal and GND for all the applications. Consider adding RC network at the supply pin (VS) of the controller to improve decoupling against the power line disturbances.
- Make the high-current path from the board input to the load, and the return path, parallel and close to each other to minimize loop inductance.
- Place the external MOSFETs close to the controller GATE drive pins (G1PU/PD and G2) such that the GATE of the MOSFETs are close to the controller GATE drive pins and forms a shorter GATE loop. Consider adding a place holder for a resistor in series with the Gate of each external MOSFET to damp high frequency oscillations if need arises.
- Place a TVS diode at the input to clamp the voltage transients during hot-plug and fast turn-off events.
- Place the external boot-strap capacitor close to BST and SRC pins to form very short loop.
- Connect the ground connections for the various components around the TPS1210x-Q1 directly to each other, and to the TPS1210x-Q1 GND, and then connected to the system ground at one point. Do not connect the various component grounds to each other through the high current ground line.

10.4.2 Layout Example

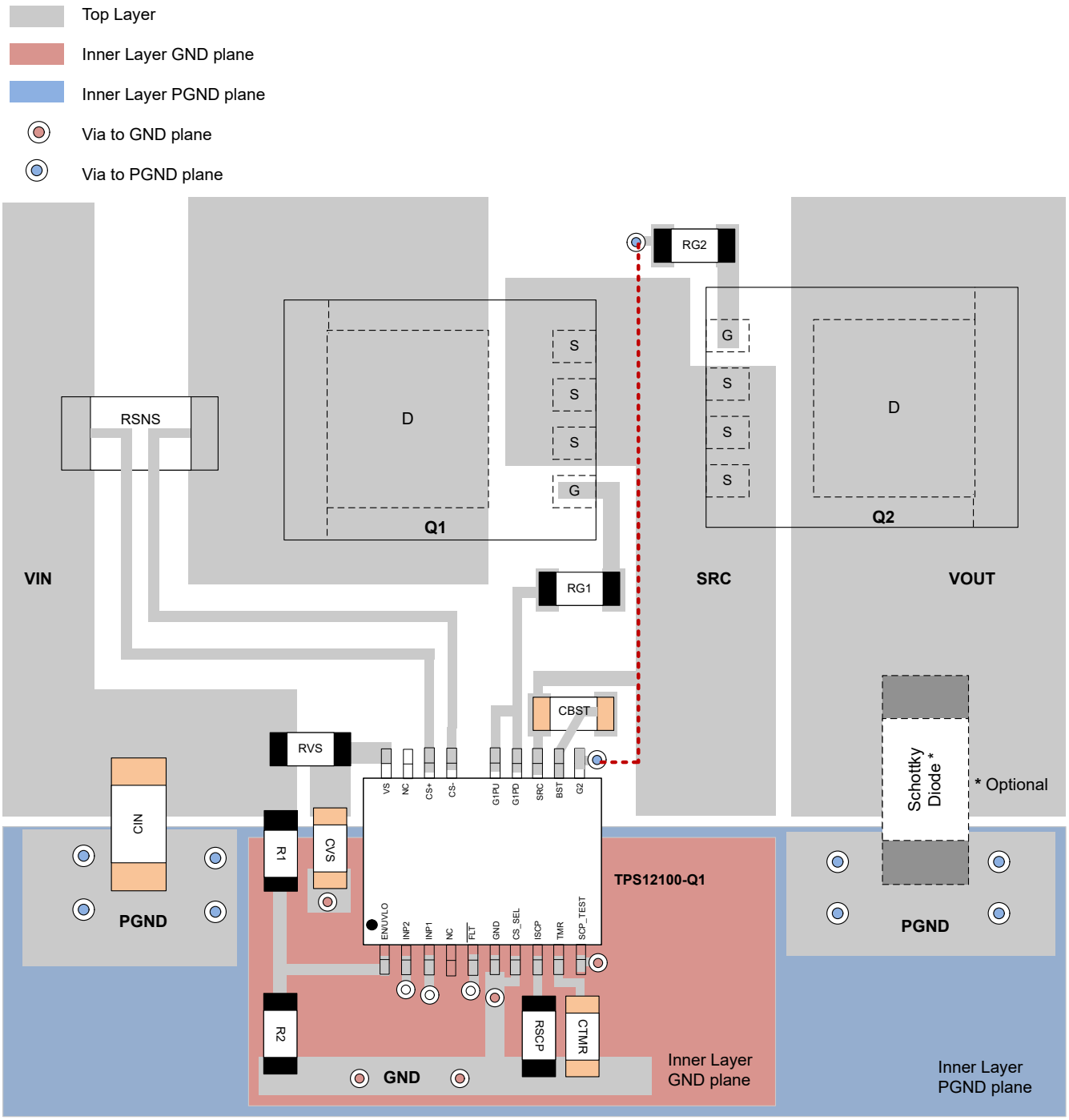


図 10-12. Typical PCB Layout Example for TPS1210-Q1 With B2B MOSFETs

ADVANCE INFORMATION

11 Device and Documentation Support

11.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

11.2 サポート・リソース

テキサス・インスツルメンツ E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計で必要な支援を迅速に得ることができます。

リンクされているコンテンツは、各寄稿者により「現状のまま」提供されるものです。これらはテキサス・インスツルメンツの仕様を構成するものではなく、必ずしもテキサス・インスツルメンツの見解を反映したものではありません。テキサス・インスツルメンツの使用条件を参照してください。

11.3 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.
すべての商標は、それぞれの所有者に帰属します。

11.4 静電気放電に関する注意事項

この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

11.5 用語集

テキサス・インスツルメンツ用語集　　この用語集には、用語や略語の一覧および定義が記載されています。

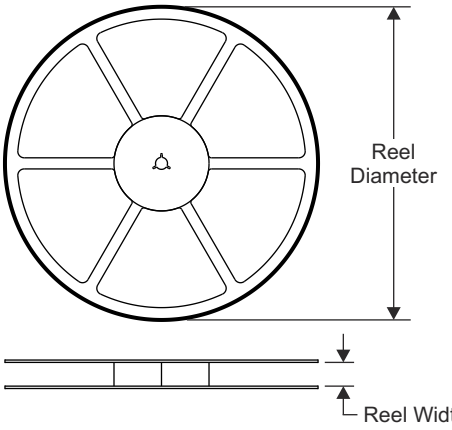
12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

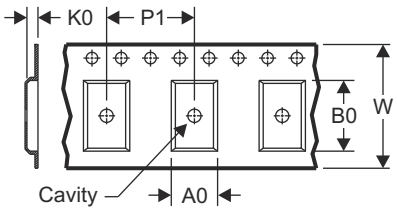
ADVANCE INFORMATION

12.1 Tape and Reel Information

REEL DIMENSIONS

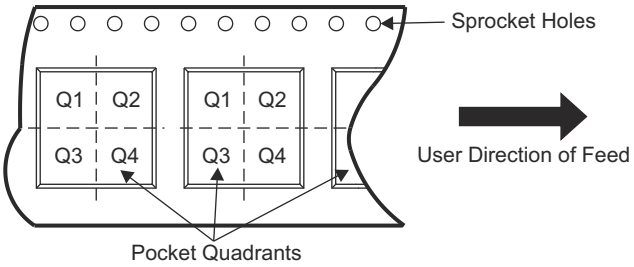


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

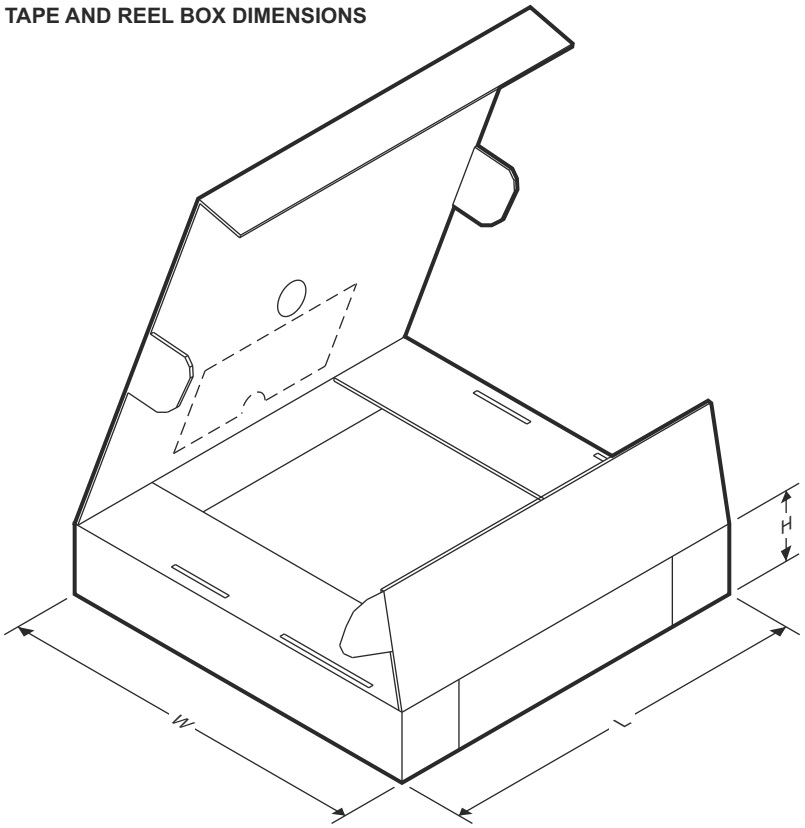


Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PTPS12100QDGXRQ1	VSSOP	DGX	19	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1
PTPS12101QDGXRQ1	VSSOP	DGX	19	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1

ADVANCE INFORMATION

ADVANCE INFORMATION

TAPE AND REEL BOX DIMENSIONS



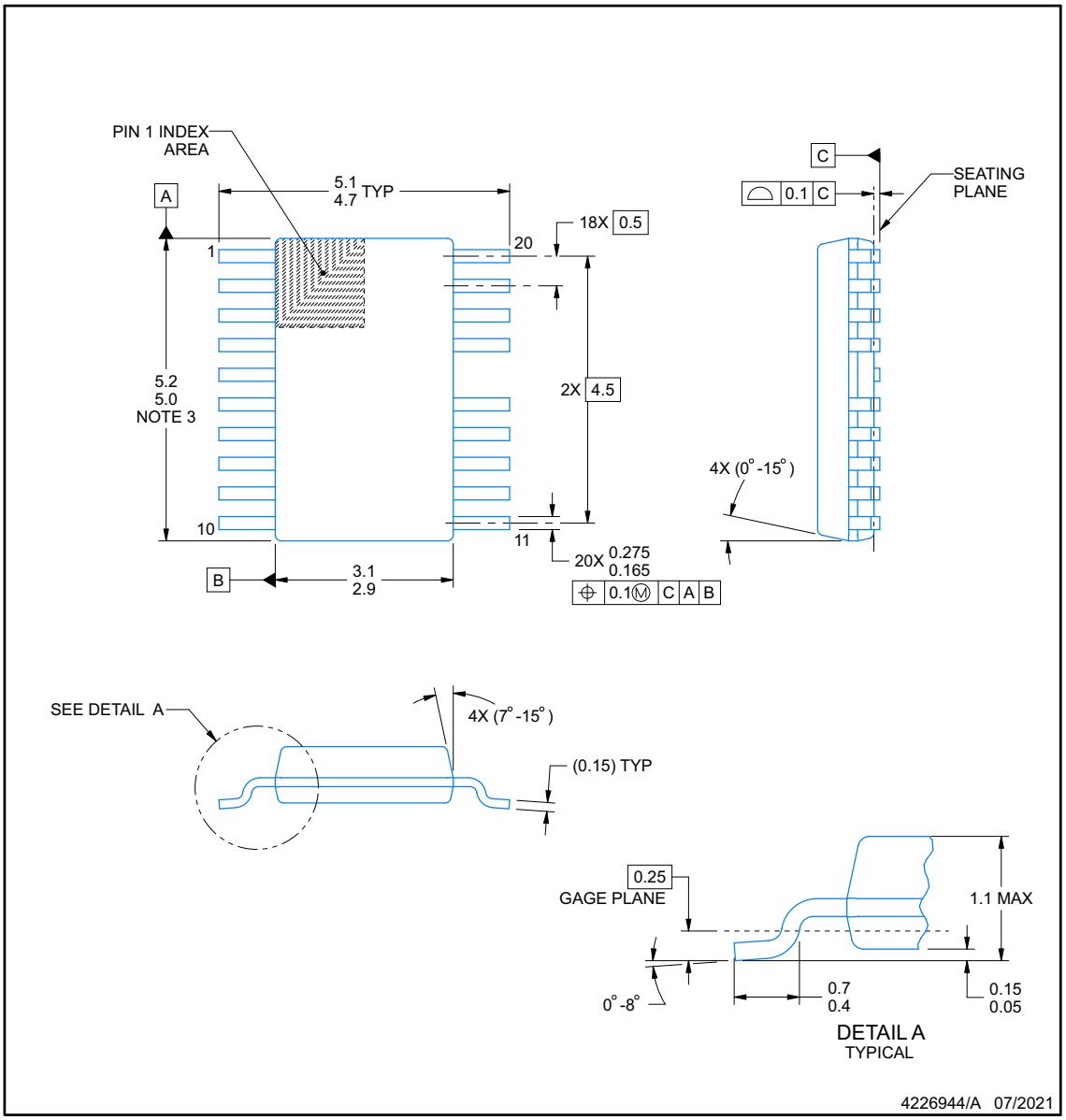
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PTPS12100QDGXRQ1	VSSOP	DGX	19	5000	356.0	356.0	35.0
PTPS12101QDGXRQ1	VSSOP	DGX	19	5000	356.0	356.0	35.0

PACKAGE OUTLINE

DGX0019A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of July 2021.
5. Features may differ or may not be present.

ADVANCE INFORMATION

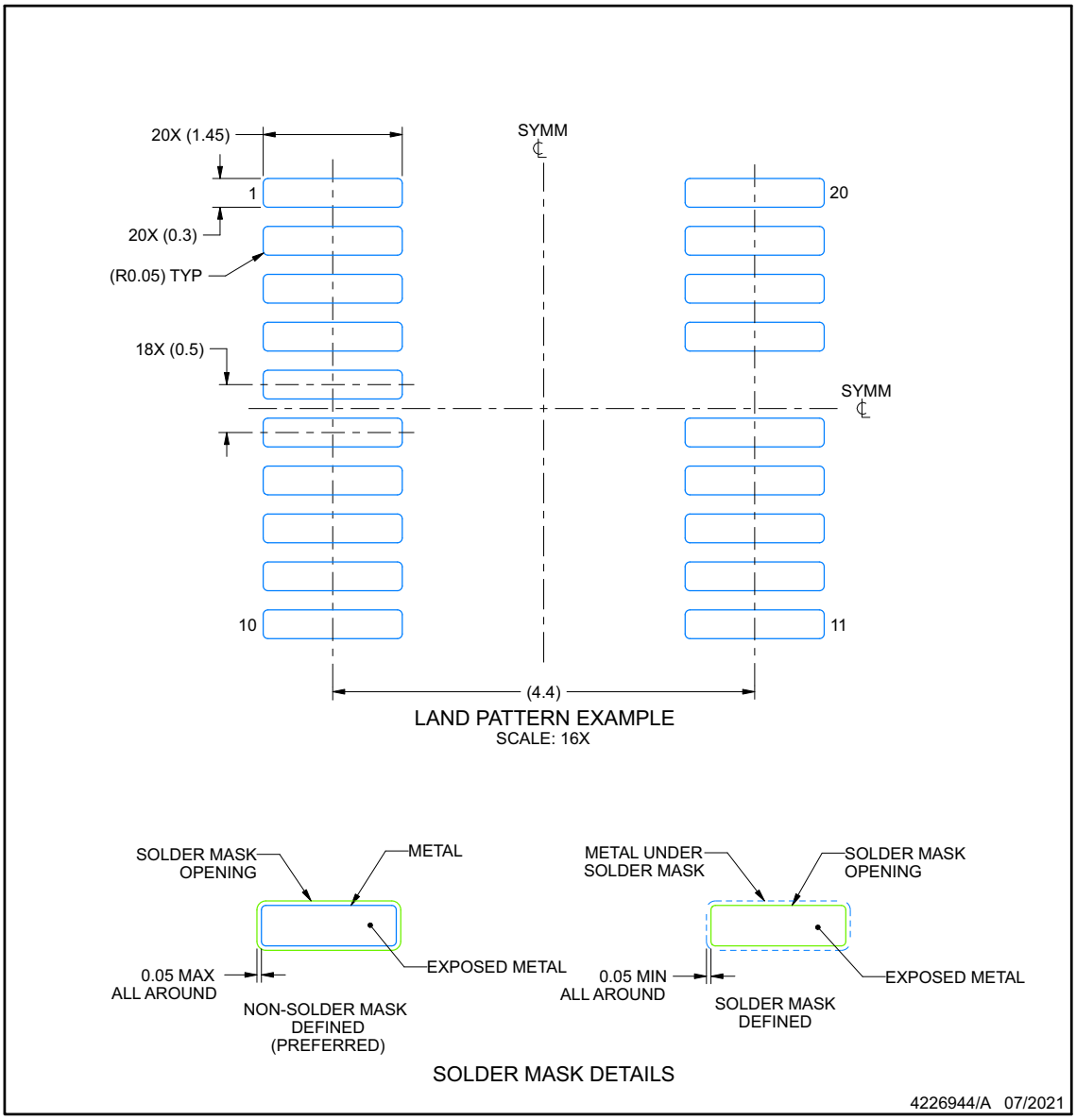
ADVANCE INFORMATION

EXAMPLE BOARD LAYOUT

DGX0019A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

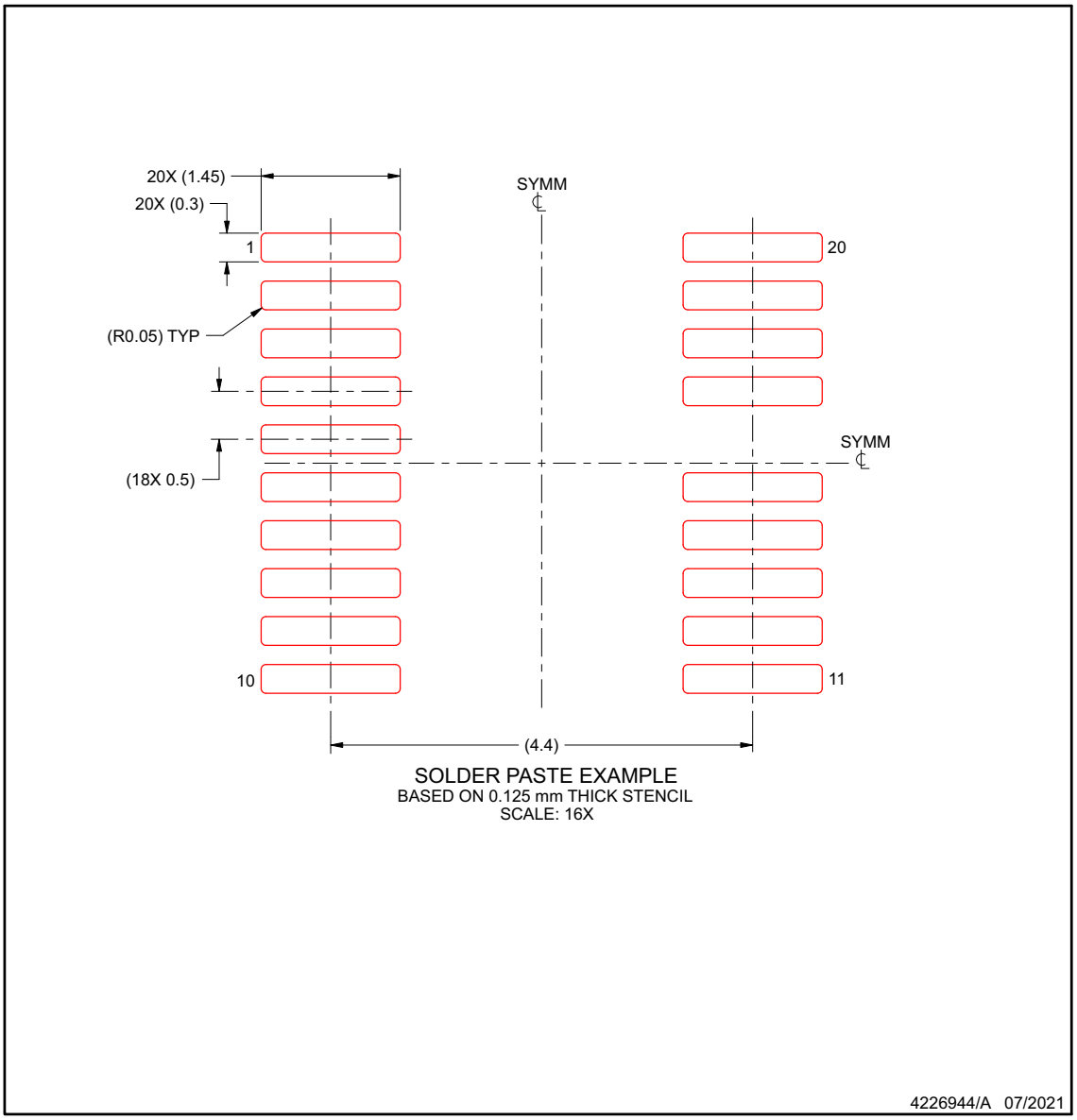
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGX0019A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 16X

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

ADVANCE INFORMATION

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PTPS12100QDGXRQ1	ACTIVE	VSSOP	DGX	19	5000	TBD	Call TI	Call TI	-40 to 125		Samples
PTPS12101QDGXRQ1	ACTIVE	VSSOP	DGX	19	5000	TBD	Call TI	Call TI	-40 to 125		Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

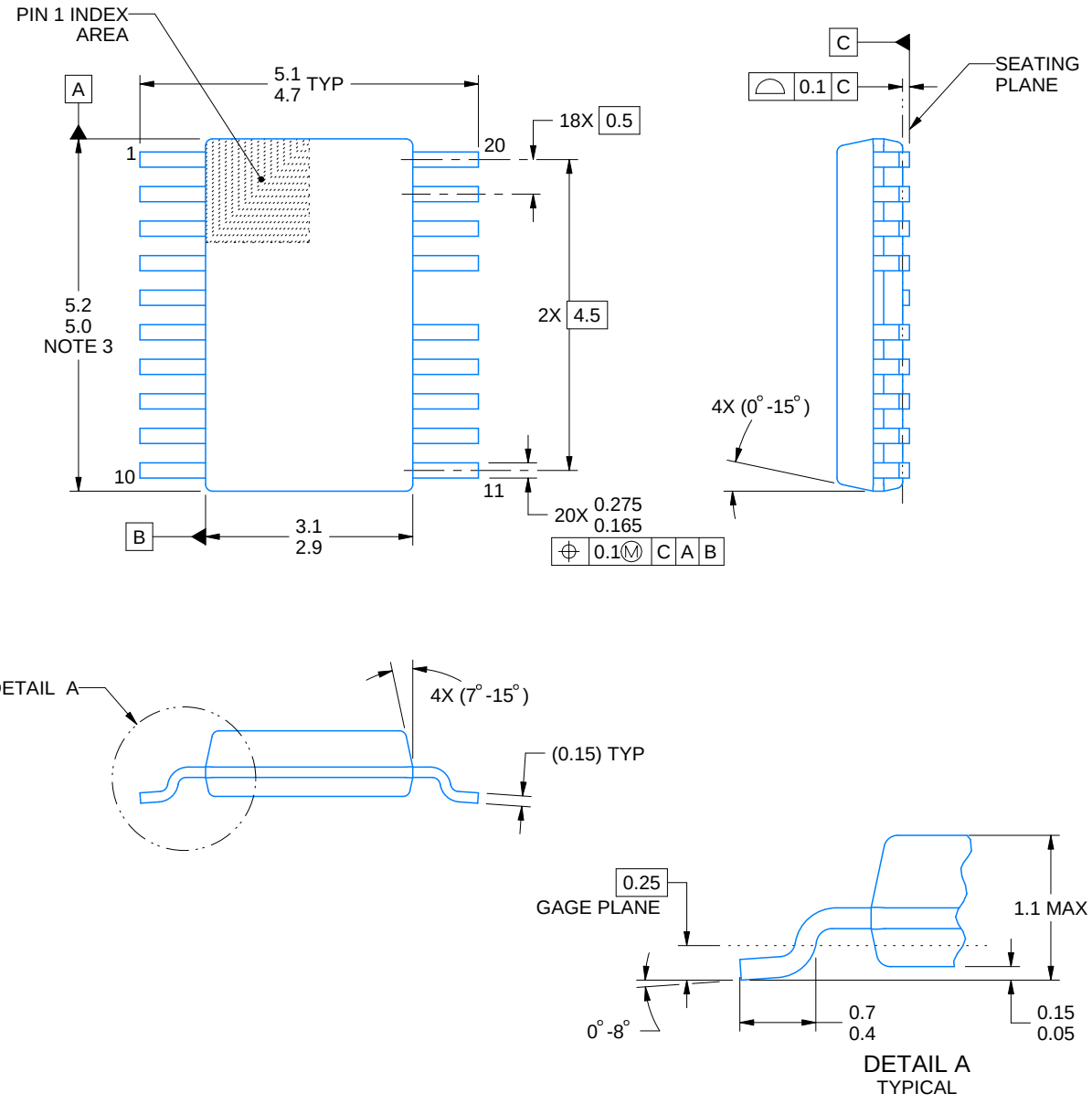
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OUTLINE

DGX0019A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



PowerPAD is a trademark of Texas Instruments.

NOTES:

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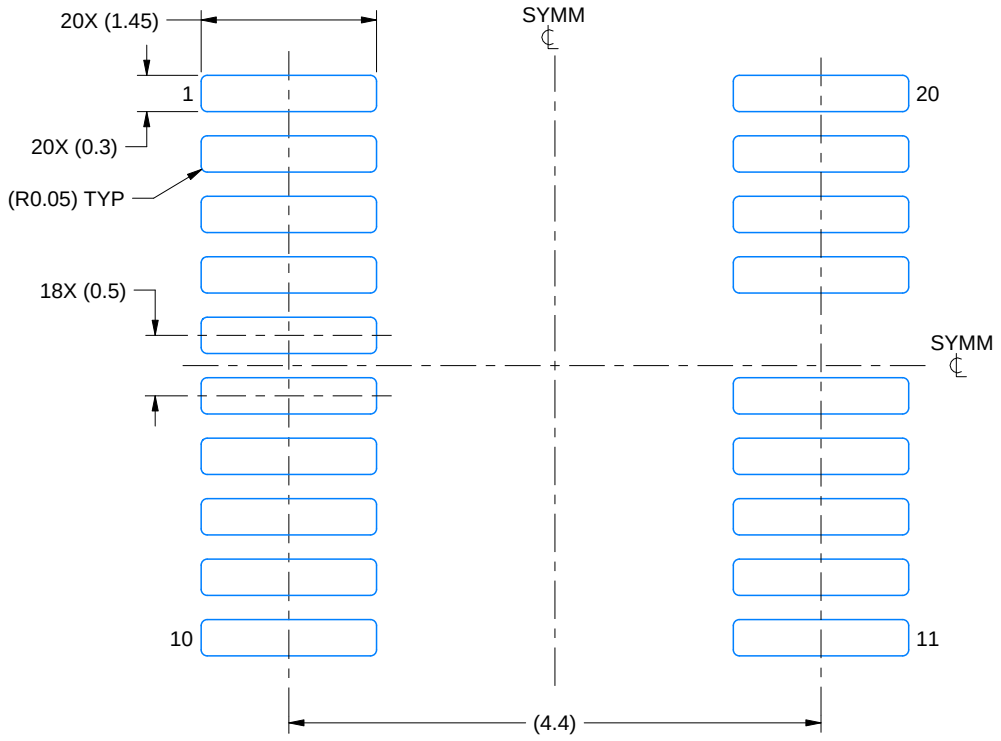
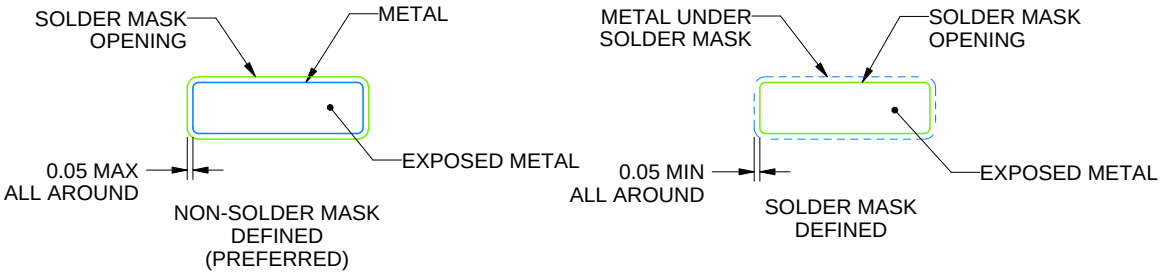
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of July 2021.
5. Features may differ or may not be present.



LAND PATTERN EXAMPLE
SCALE: 16X



SOLDER MASK DETAILS

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NOTES: (continued)

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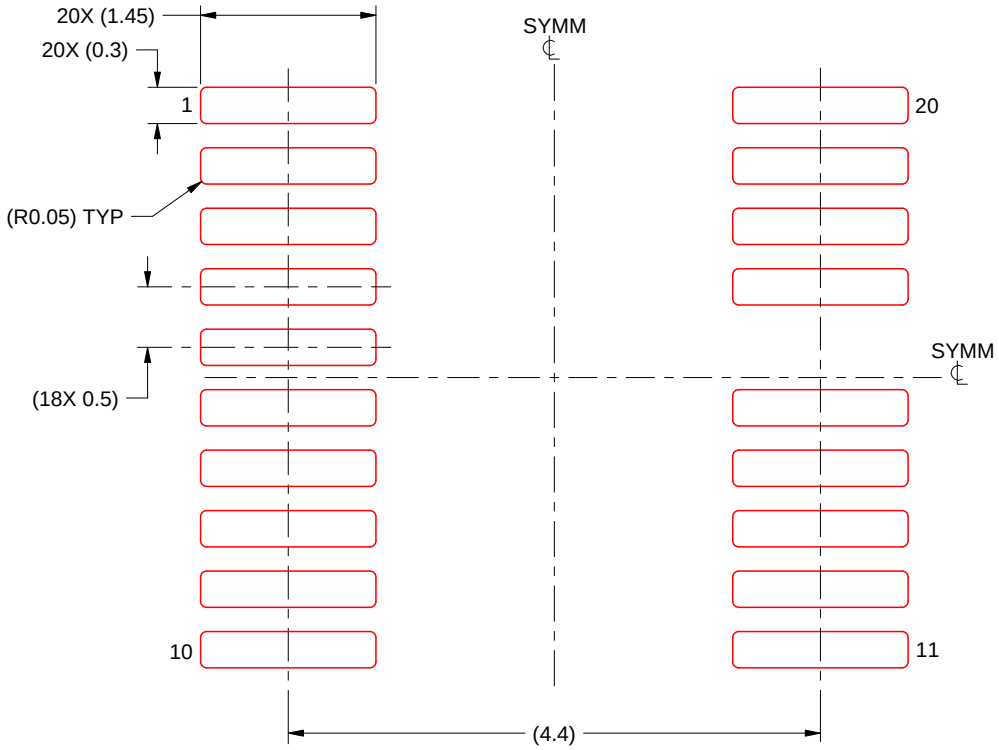
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 16X

4226944/A 07/2021

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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